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	DATENTS ONLY		
To the Director of the U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.			
10.11	Name of conveying party(ies): Masashi KUME Tomomichi TAKATSU		
	Name and Address of receiving party(ies):		
•	DENKI KAGAKU KOGYO KABUSHIKI KAISHA 1-1, Nihonbashi-Muromachi 2-chome, Chuo-ku, Tokyo 103-8338, JAPAN		
<b>i.</b>	Nature of conveyance:  X		
	Execution Date(s): October 20, 2011		
1.	Application number(s) or patent number(s):  This document is being filed together with a new application:  The execution date(s) of the application is/are:  The execution date(s) of the application is/are:  The title is: ADHESIVE SHEET AND METHOD OF BACKGRINDING  SEMICONDUCTOR WAFER  OR		
	<ul> <li>☐ This document is being filed after filing of the application:</li> <li>(a) Patent Application No(s). 13/318,436, filed November 1, 2011; or</li> <li>(b) Patent No(s). , issued</li> </ul>		
5.	Name and address of party to whom correspondence concerning document should be mailed:  STEIN MCEWEN, LLP Our Docket: 0271.1004  Attention: Michael D. Stein 1400 Eye St., N.W., Suite 300  Washington, D.C. 20005		
6.	Total number of applications and patents involved:1		
7.	Total fee (37 CFR 3.41)(\$ 40.00 per Patent or Application in Assignment)  Enclosed  Authorized to be charged to Deposit Account No. 503333.		
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Michael D. Stein, Reg. No. 37,240 Name of Person Signing

Signature

Total number of pages including cover sheet: 2

Attorney Docket No.: 0271.1004

## U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by

(insert Name(s) & Address(es) of ASSIGNEE(\$))

DENKI KAGAKU KOGYO KABUSHIKI KAISHA 1-1, Nihonbashi-Muromachi 2-chome, Chuo-ku, Tokyo 103-8338, JAPAN

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

ADHESIVE SHEET AND METHOD OF BACKGRINDING SEMICONDUCTOR WAFER relating to International Patent Application PCT/JP2010/059210 and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not se executed, was:

(9) expented ou :	nsert date of execution of application, if not concurrent)
	ny registered ariorney of STEIN MCEWEN, LLP, 1400 Eye St., W., Sulte 300, Washington, D.C. 2005 (202/216-9505) is hereby uthorized to insort in (b) the specified data, when known.
substitute, release or recognition to thereof (collectively, her granted and including any extensions thereof (collectively, her The ASSIGNOR agree(s), when requested by said a to do all acts which the ASSIGNEE may deem necessary, deal to do all acts which the ASSIGNEE may deem necessary.	SSIGNEE and without charge to but at the expedient, for securing, maintaining and enforcing protection for reble or expedient, for securing, maintaining and enforcing protection for securing application(s) and the issuance of said Letters Patent(s), in any said said application of other legal proceeding which may arise or by and in any litigation or other legal proceeding which may arise or by and in any litigation of other legal proceeding separate assignments and all limited to executing all papers, including separate assignments and ny, and obtaining and producing evidence.

PATENT REEL: 027174 FRAME: 0541

**RECORDED: 11/02/2011**